

75 AMP PRESS FIT TVS DIODES (PRELIMINARY)

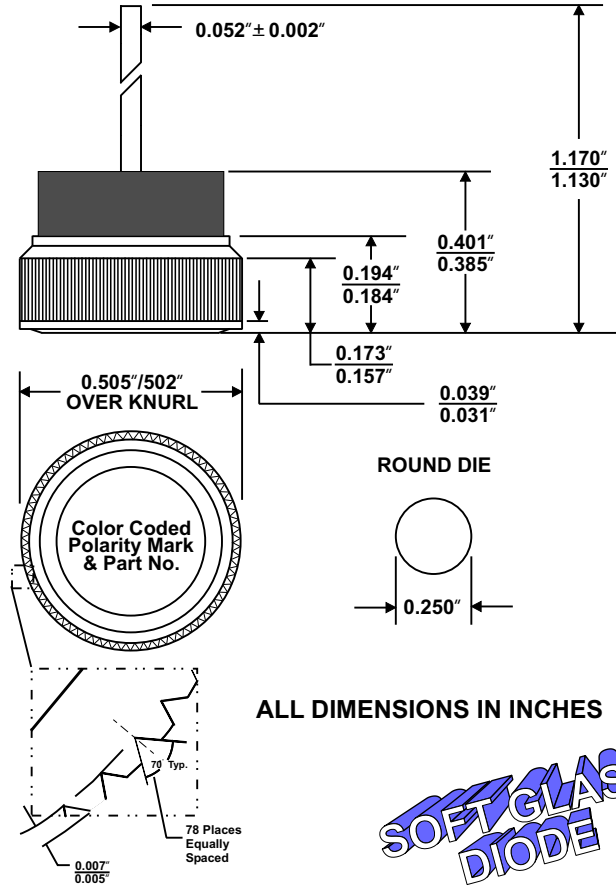
FEATURES

- VOID FREE VACUUM DIE SOLDERING FOR MAXIMUM MECHANICAL STRENGTH AND HEAT DISSIPATION (Solder Voids: Typical $\leq 2\%$, Max. $\leq 10\%$ of Die Area)
- LARGE DIE FOR HIGH POWER HEAVY DUTY PERFORMANCE
- HIGH HEAT HANDLING CAPABILITY WITH VERY LOW THERMAL STRESS
- Proprietary SOFT GLASS[®] junction passivation for superior reliability and performance
- Very low forward voltage drop
- Protects expensive automotive electronics and mobile equipment

MECHANICAL DATA

- Case: Nickel plated copper
- Finish: All external surfaces are corrosion resistant and the contact areas are readily solderable
- Soldering Temperature: 250 °C maximum
- Mounting Position: Any. Maximum force used for diode insertion to be 12 KN
- Polarity: Color coded polarity mark and part number on cap base (ANODE on LEAD; Part No.=TVS7524PFA) (CATHODE on LEAD; Part No.=TVS7524PFC)

MECHANICAL SPECIFICATION



MAXIMUM RATINGS & ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified.

PARAMETER (TEST CONDITIONS)	SYMBOL	RATINGS		UNITS
		TVS7524PFC	TVS7524PFA	
Series Number				
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	23	23	VOLTS
Working Peak Reverse Voltage	V _{RWM}			
Maximum DC Blocking Voltage	V _{DC}			
Breakdown Voltage (I _R = 100 mA dc, T _c = 25 °C)	V _(BR)	24 Min / 32 Max	24 Min / 32 Max	
Average Forward Rectified Current	I _O	75	75	AMPS
Non-repetitive Peak Forward Surge Current (Half wave, single phase, 60 Hz sine applied to rated load)	I _{FSM}	800	800	
Repetitive Peak Reverse Surge Current (Time Constant = 10 mSec Duty Cycle $\leq 1.0\%$, T _c = 25 °C)	I _{RSM}	150	150	
Instantaneous Forward Voltage (I _F = 100A@ 300 μ Secpulse, T _c = 25°C)	V _F	1.05 0.97 (Typical)	1.05 0.97	VOLTS
Maximum DC Reverse Current (V _R = 20V DC, T _c = 25 °C)	I _R	200	200	nA
Maximum Thermal Resistance, Junction to Case	R _{θJC}	0.75	0.75	°C/W
Junction Operating & Storage Temperature Range	T _J , T _{STG}	-65 to +175	-65 to +175	°C